## Declaration, Power of Attorney and Petition

Page 1 of 3

WE (I) the undersigned inventor(s), hereby declare(s) that:

My residence, post office address and citizenship are as stated below next to my name,

We (I) believe that we are (I am) the original, first and joint (sole) inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled CUTTING INSERT INCLUDING CUBIC BORON NITRIDE BASED ULTRA-HIGH PRESSURE SINTERED MATERIAL

| is attached hereto.              |                  |  |
|----------------------------------|------------------|--|
| was filed on                     | as               |  |
| Application Serial No.           |                  |  |
| and amended on                   | ·                |  |
| was filed as PCT international a | application      |  |
| Number PCT/JP03/02362            |                  |  |
| on 28/February/2003              | ,                |  |
| and was amended under PCT A      | rticle 19        |  |
| on                               | (if applicable). |  |

We (I) acknowledge the duty to disclose information known to be material to the patentability of this application as defined in Section 1.56 of Title 37 Code of Federal Regulations.

We (I) hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed. Prior Foreign Application(s)

| Application No. | Country | Day/Month/Year | Priority<br>Claimed |
|-----------------|---------|----------------|---------------------|
| 2001- 259275    | Japan   | 29/08/2001     | ☐ Yes 🗵 No          |
| 2001-308414     | Japan   | 04/10/2001     | ☐ Yes ☒ No          |
| 2002-117578     | Japan   | 19/04/2002     | 🛚 Yes 🔲 No          |
| 2002-117580     | Japan   | 19/04/2002     | 🛚 Yes 🗌 No          |
|                 |         |                | ☐ Yes ☐ No          |

10/01

Page 2 of 3 Declaration

| We (I) hereby claim the benefit unapplication(s) listed below.   | inder Title 35, United Sta  | tes Code, § 119(e) of any United Stat  | es provisional                               |  |  |  |
|--|---|--|--|--|--|--|
| (Application Number  | er)   | (Filing Date)  |  |  |  |  |
| (Application Number  | er) –   | (Filing Date)  |  |  |  |  |
| any PCT International application des<br>each of the claims of this application<br>the manner provided by the first paragi   | signating the United State<br>is not disclosed in the pri<br>raph of 35 U.S.C. § 112, I<br>in 37 CFR § 1.56 which I | ny United States application(s), or und its, listed below and, insofar as the subsor United States or PCT International acknowledge the duty to disclose inforcecame available between the filing dates application.   | pject matter of application in rmation which |  |  |  |
| Application Serial No.   | Filing Date   | Status (pending, p<br>abandoned  |  |  |  |  |
|  |   |  | · · · ·                                      |  |  |  |
|  |   |  |  |  |  |  |
| And we (I) hereby appoint the fo   | llowing registered practiti   | oner(s):   |  |  |  |  |
| 22850  |   |  |  |  |  |  |
| as our (my) attorneys, with full powers of substitution and revocation, to prosecute this application and to transact all business in the Patent Office connected therewith; and we (I) hereby request that all correspondence regarding this application be sent to |   |  |  |  |  |  |
|  | 22850   |  |  |  |  |  |
| on information and belief are believed<br>that willful false statements and the lik  | I to be true; and further the so made are punishable le and that such willful                                       | own knowledge are true and that all state these statements were made with the by fine or imprisonment, or both, under false statements may jeopardize the value of the value o | he knowledge<br>r Section 1001               |  |  |  |
| Itsurou TAJIMA   |   | Residence Saitama-shi, Japan   | 1  |  |  |  |
| NAME OF FIRST SOLE INVENTOR  | —   | JPX  |  |  |  |  |
| (1-  | <del>,</del>  |  | <del></del>                                  |  |  |  |
| Signature of Inventor  |   | Citizen of: Japan  | <del>-</del>                                 |  |  |  |
|  | C   | Mailing Address: <u>c/o MITSUBISHI MATE</u><br>CORPORATION, Central Research Institute, Nak<br>Senter, 1002-14, Mukaiyama, Naka-cho, Naka-gu   | a Research                                   |  |  |  |
| October 8, 2004  |   | paraki-ken, Japan  |  |  |  |  |
| Date   |   |  |  |  |  |  |

1 9.49

Page 3 of 3 Declaration

| ·  |   |
|--|---|
| Jaokata SEKI                                 | Residence: Naka-gun, Japan  |
| NAME OF SECOND JOINT INVENTOR                | JPV   |
| Naokata Seki                                 | Citizen of: Japan   |
| Signature of Inventor                        | Mailing Address: _c/o MITSUBISHI MATERIALS CORPORATION, Central Research Institute, Naka Research Center, 1002-14, Mukaiyama, Naka-cho, Naka-gun,       |
| October 8, 2004  Date                        | Ibaraki-ken, Japan  |
| 0  | ·   |
| Mazuo YAMAMOTO  NAME OF THIRD JOINT INVENTOR | Residence: Saitama-shi, Japan   |
| NAIVE OF THIRD JOIN I INVENTOR               |   |
| Signature of Inventor                        | Citizen of: Japan   |
| Signature of Inventor                        | Mailing Address: <u>c/o MITSUBISHI MATERIALS</u> CORPORATION, Central Research Institute, Naka Research Center, 1002-14, Mukaiyama, Naka-cho, Naka-gun, |
| October 8, 2004                              | Ibaraki-ken, Japan  |
| NAME OF FOURTH JOINT INVENTOR                | Residence:  |
|  | Citizen of:   |
| Signature of Inventor                        | Mailing Address:  |
|  |   |
| Date   |   |
| NAME OF FIFTH JOINT INVENTOR                 | Residence:  |
|  | Citizen of:   |
| Signature of Inventor                        | Mailing Address:  |
|  |   |
| Date   |   |